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THERMOSETTING RESIN COMPOSITION AND SEMICONDUCTOR DEVICE USING
THE SAME

ABSTRACT OF THE DISCLOSURE

5 A thermosetting resin composition usable for sealing a gap formed between a printed circuit board and a semiconductor element in a semiconductor package having a face-down structure; a semiconductor device comprising a printed circuit board, a semiconductor element, and the thermosetting resin composition mentioned above, wherein a gap formed between the printed circuit board and the semiconductor element is sealed by the thermosetting resin composition; and a process for manufacturing the semiconductor device.

Figure 1



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